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(54) Title: METHOD OF FABRICATING A COATED PROCESS CHAMBER COMPONENT

(57) Abstract: A method of fabricating a process chamber component that has a ceramic form with grains and grain boundary regions. In the method, the component is bead blasted to provide a surface having a relatively low roughness average of less than about 150 microinches. The component is dipped into a soluting having a concentration that is sufficiently low to reduce etching of grain boundary regions of the ceramic form. A metal coating is formed over at least a portion of the ceramic form. The component fabricated by this method can tolerate thicker deposits of sputtered material in a sputtering process without the sputtered deposit accumulating causing spalling of the coating of the component.



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